

Amendments to the Claims:

This following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

Listing of Claims:

Claims 1-13 (Canceled).

14. (Currently Amended) A substrate for mounting semiconductor device, comprising:

plural semiconductor-mounting substrate portions, each for mounting a respective semiconductor device,

a connecting portion for connecting said semiconductor-mounting substrate portions ~~substrates~~; and

a registration mark portion,

wherein each of said semiconductor-mounting substrate portions ~~portion~~ comprises wirings that

include an external connection terminal and a wire bonding terminal provided in an outer side than said external connection terminal, and

said connecting portion comprises an electrically conductive layer.

15. (Currently Amended) A substrate for mounting a semiconductor device according to claim 14, wherein said electrically conductive layer and said ~~wiring~~ wirings are made of the same material.

16. (Currently Amended) A substrate for mounting a semiconductor device as claimed in claim 14, wherein nickel and gold are plated on a surface of said ~~wiring~~ wirings.

17. (Currently Amended) A substrate for mounting a semiconductor devices as claimed in claim 15, wherein nickel and gold is plated on a surface of said ~~wiring~~wirings.

18. (Withdrawn) A method of fabricating a substrate for mounting a semiconductor device thereon comprising:

plural semiconductor-mounting substrate portions, each for mounting a semiconductor device;

a connection portion for connecting said plural substrate portions and having an electrically conductive layer; and

a registration mark portion,

wherein said semiconductor-mounting substrate portion comprises wirings that include an external connection terminal and a wire bonding terminal provided in outer side than said external connection terminal, and

wherein said fabrication method comprises a step of forming said conductive layer of said wirings and said connecting portions on a resin base material in a lump.

19. (Withdrawn) A method of fabricating a substrate for mounting a semiconductor device thereon according to claim 18, further comprising a step of; forming said wirings and said conductive layer by plating.

20. (Withdrawn) A method of fabricating a substrate for mounting a semiconductor device thereon according to claim 18, further comprising a step of plating the surface of said wirings with nickel and gold.

21. (Withdrawn) A method of fabricating a substrate for mounting a semiconductor device thereon according to claim 19, further comprising a step of plating the surface of said wrings with nickel and gold.

22. (Withdrawn) A method of manufacturing a semiconductor package comprising steps of:

mounting a semiconductor device on said substrate for mounting the semiconductor device by a die-bonding wire;

connecting a connection terminal of said semiconductor device to said wire bonding terminal with bonding wire;

sealing said semiconductor device with an encapsulating resin; and

forming a solder bump in said external connection terminal;

wherein said substrate for mounting the semiconductor device is the substrate according to any one of claims 14-17 or the substrate manufactured according to the fabricating method as claimed in any one of claims 18-20.

23. (Withdrawn) A method of fabricating a semiconductor package according to claim 21, wherein said die bond material is a die bonding tape.

24. (New) A substrate for mounting a semiconductor device as claimed in claim 14, wherein said wire bonding terminal is a terminal for connecting a wire from said semiconductor device thereto.

25. (New) A substrate for mounting a semiconductor device as claimed in claim 24, wherein said external connection terminal is for electrically connecting said substrate to an outer wiring.

26. (New) A substrate for mounting a semiconductor device as claimed in claim 14, wherein said external connection terminal is for electrically connecting said substrate to an outer wiring.